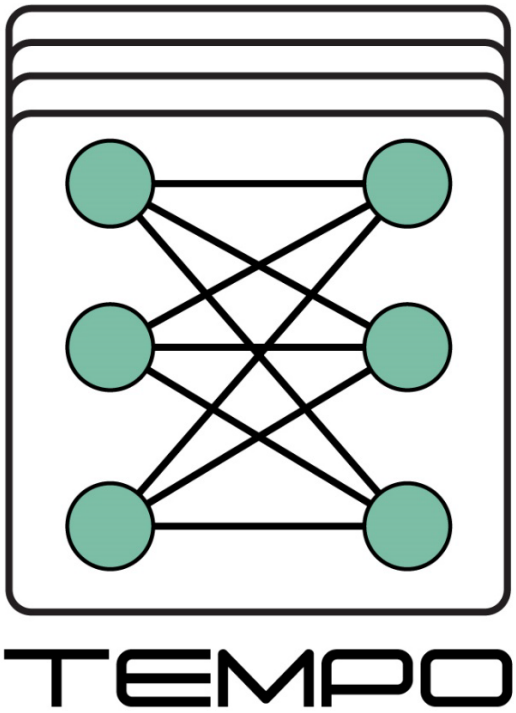
Technology & Hardware for nEuromorphic coMPuting

- ECSEL Research and Innovation Actions (RIA*) –



Deliverable 3.1
– 3D Microbump Technology Roadmap –

Work Package	WP 3
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Responsible Partner	IMEC
Name	Microbump Technology Roadmap
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ECSEL Joint Undertaking

Publishable Summary

This deliverable is a short report on the technology roadmap as defined by IMEC's 3D research program for microbump interconnections. The scope covers the different pitch requirements for D2D, D2W and W2W bonding applications.

For this deliverable IMEC has been focused upon fine pitch bonding related activities, primarily aimed at hybrid bonding options which are required to enable pine pitch interconnections. This report summarizes the specifications required to enable fine pitch hybrid bonding plus the general status of maturity of the processes. This report also contains the technology landscape roadmap for more relaxed pitch interconnects enabling context for the TEMPO related focus point of fine pitch hybrid bonding.